Semiconductor Device Type: **D5X-VQFN-16-4x4x1.0mm-MatteTin**

Sub-Component	Basic Substance	CAS Number	% Total Weight	mg/part	ppm
Mold Compound	Epoxy Resin	Trade Secret	3.27	1.36	32725
Mold Compound	Phenol Resin	Trade Secret	1.40	0.58	14025
Mold Compound	Silica (Amorphous) A	60676-86-0	37.40	15.60	374000
Mold Compound	Silica (Amorphous) B	7631-86-9	3.27	1.36	32725
Mold Compound	Metal Hydroxide	Trade Secret	1.17	0.49	11688
Mold Compound	Carbon Black	1333-86-4	0.23	0.10	2338
Leadframe	Copper	7440-50-8	38.90	16.22	388992
Leadframe	Iron	7439-89-6	0.99	0.41	9876
Leadframe	Phosphorus	7723-14-0	0.05	0.02	504
Leadframe	Zinc	7440-66-6	0.05	0.02	504
Leadframe	Silver	7440-22-4	0.32	0.13	3225
Die Attach Epoxy	Silver	7440-22-4	1.28	0.53	12812
Die Attach Epoxy	exo-1,7,7-trimethylbicyclo[2.2.1]hept-2- yl methacrylate	7534-94-3	0.01	0.01	131
Die Attach Epoxy	Dodecyl acrylate	2156-97-0	0.01	0.01	131
Die Attach Epoxy	1,6-Hexanediol diacrylate	13048-33-4	0.00	0.00	13
Die Attach Epoxy	1-Methyl-2-pyrrolidone	872-50-4	0.00	0.00	13
Bonding Wire	Copper	7440-50-8	0.77	0.32	7663
Bonding Wire	Palladium	7440-05-3	0.02	0.01	198
Bonding Wire	Gold	7440-57-5	0.00	0.00	40
Die	Doped Silicon	7440-21-3	7.89	3.29	78900
Plating on External Leads	Tin	7440-31-5	2.95	1.23	29500
		TOTALS:	**100.00**	**41.70**	**1,000,000**

41.70 mg Total Mass

Package Homogeneous Materials

19.49	**(mg) Total**	**Mold Compound**	**% of Total Weight**	**46.75**
	Epoxy Resin	Trade Secret	7.00	
	Phenol Resin	Trade Secret	3.00	
	Silica (Amorphous) A	60676-86-0	80.00	
	Silica (Amorphous) B	7631-86-9	7.00	
	Metal Hydroxide	Trade Secret	2.50	
	Carbon Black	1333-86-4	0.50	
		Total	**100.00**	
16.81	**(mg) Total**	**Leadframe**	**% of Total Weight**	**40.31**
	Copper	7440-50-8	96.50	
	Iron	7439-89-6	2.45	
	Phosphorus	7723-14-0	0.13	
	Zinc	7440-66-6	0.13	
	Silver	7440-22-4	0.80	
		Total	**100.00**	
0.55	**(mg) Total**	**Die Attach Epoxy**	**% of Total Weight**	**1.31**
	Silver	7440-22-4	97.80	
	exo-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl methacrylate	7534-94-3	1.00	
	Dodecyl acrylate	2156-97-0	1.00	
	1,6-Hexanediol diacrylate	13048-33-4	0.10	
	1-Methyl-2-pyrrolidone	872-50-4	0.10	
		Total	**100.00**	
0.33	**(mg) Total**	**Bonding Wire**	**% of Total Weight**	**0.79**
	Copper	7440-50-8	97.00	
	Palladium	7440-05-3	2.50	
	Gold	7440-57-5	0.50	
		Total	**100.00**	
3.29	**(mg) Total**	**Die**	**% of Total Weight**	**7.89**
	Doped Silicon	7440-21-3	100.00	
		Total	**100.00**	
1.23	**(mg) Total**	**Plating on External Leads**	**% of Total Weight**	**2.95**
	Tin	7440-31-5	100.00	
41.70		**Total**	**100.00**	100.00

The information contained in this Material Content Declaration (MCD) consists of package-level information and is not part number specific. This information is considered to be sufficiently representative of all part numbers for the package type.

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